



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

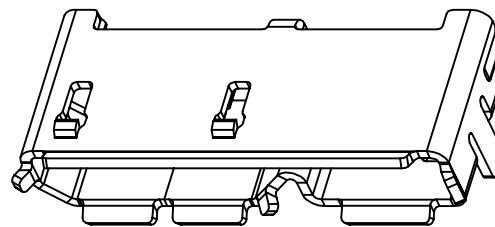
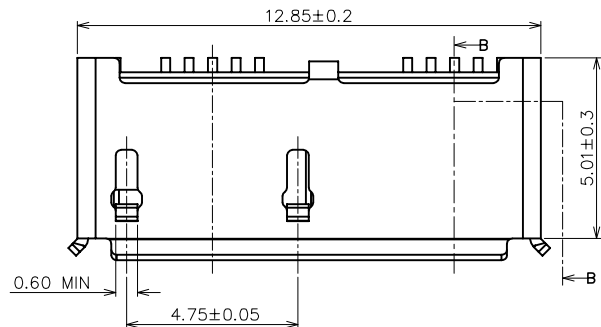
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



| REVISION RECORD | | |
|-----------------|-------------|------|
| REV | DESCRIPTION | DRFT |
| | | |



NOTES:

MECHANICAL CHARACTERISTICS:

- 1.MATING FORCE: 3.57 Kg Max.
 - 2.UNMATING: 1.0~1.6 Kg.
 - 3.LIFE TEST: 10000 CYCLES
- ELECTRICAL CHARACTERISTICS:**
- 1.CURRENT RATING: 1.5A
 - 2.CONTACT RESISTANCE: 30mΩMAX.
 - 3.DIELECTRICAL WITHSTANDING: 100V AC/1min.
 - 4.INSULATION RESISTANCE: 100MΩmin.

MATERIAL:

- 1.PLASTIC: LCP WITH 30% GF,UL 94V-0 ,Black.
- 2.TERMINAL:PHOSPHOR BRONZE, 0.2 THICKNESS.
- 3.TERMINAL PLATING:

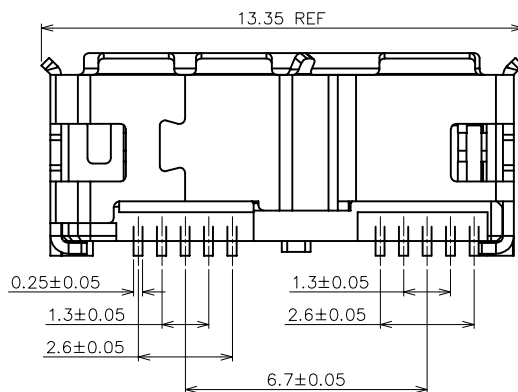
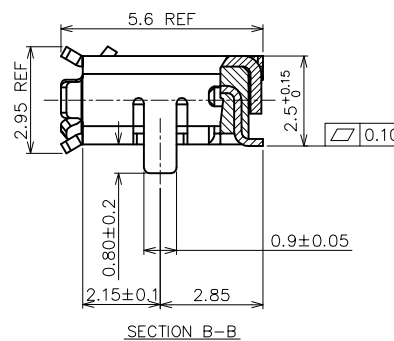
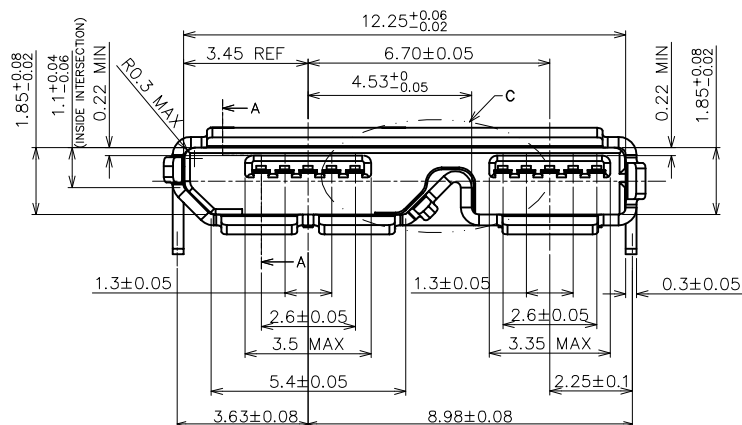
- UNDERPLATING ALL OVER NICKEL 50u"MIN.
 - CONTACT PLATING GOLD PLATING 15u"MIN
 - OTHER AREA GOLD PLATING 1u"MIN,
- 4.SHIELD: STEEL0.3 THICKNESS.

5.SHIELD PLATING:

- UNDERPLATING ALL OVER CU 20u"MIN
- PLATING ALL OVER NICKEL 50u"MIN.

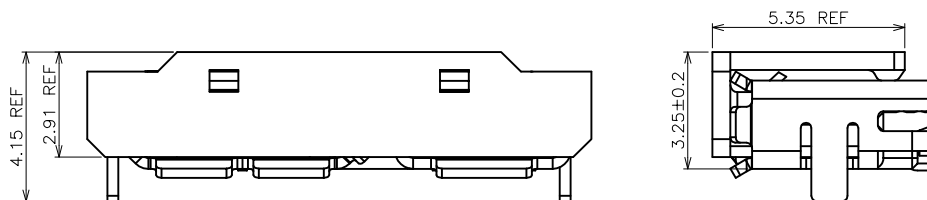
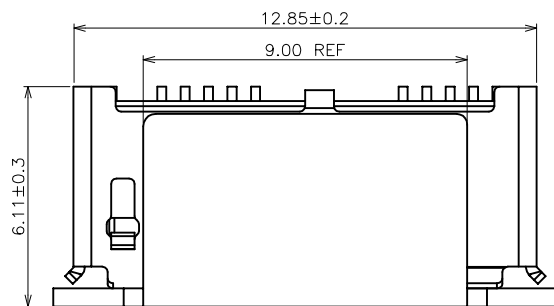
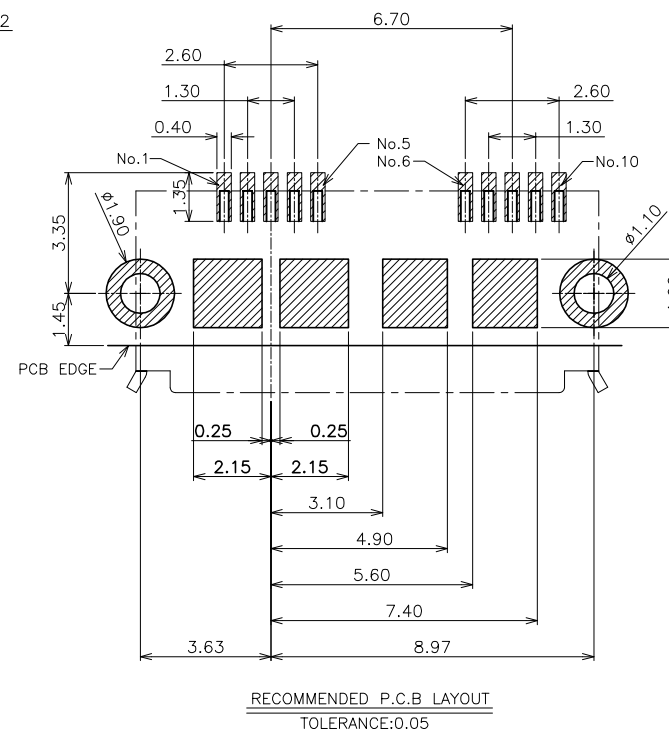
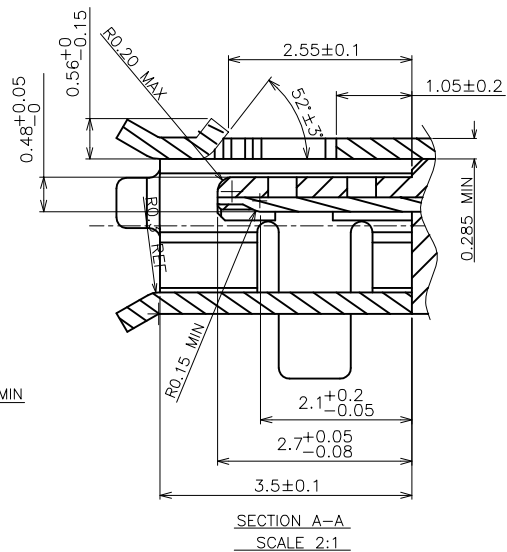
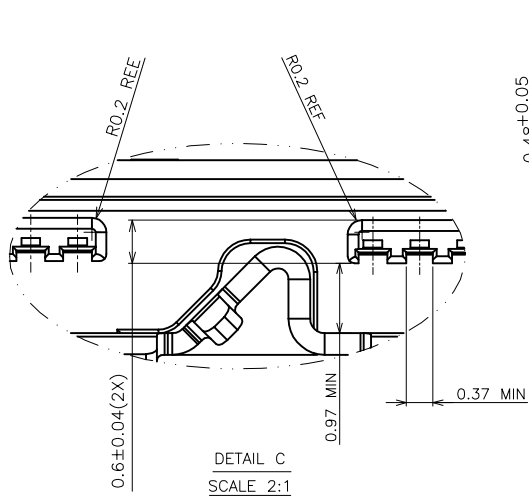
OTHERS:

- 1.OPERATION TEMPERATURE:-20°c to +80°c



| MM (INCH) | | DFTD Roy | DATE 11/20/2012 | | RoHS Compliant | |
|----------------------------|---|------------------------|-----------------|--------------------------|---------------------------------|---------|
| TOLERANCES EXCEPT AS NOTED | | CHKD | DATE | | TITLE USB 3.0 MICRO BF SMD TYPE | |
| MM | | APPVL | DATE | DRAWING NO. E8110-030-01 | | |
| . ± 0.35 | ± | MATERIAL : | | /PART NO. E8110-030-01 | | SIZE A3 |
| .0 ± 0.25 | ± | QT'Y : | | DO NOT SCALE DRAWING | | REV 01 |
| .00 ± 0.15 | ± | FINISH : | | SHEET 1 OF 2 | | |
| .000 ± 0.05 | ± | SCALE : 1:1 | | | | |
| ANGLES: X:±1° X.X:±0.5° | | THIRD ANGLE PROJECTION | | | | |

| REVISION RECORD | | |
|-----------------|-------------|------|
| REV | DESCRIPTION | DRFT |
| | | |



USB 3.0 Micro BF SMD TYPE+CAP

| | | | | | |
|----------------|----------------------------|---------------------------|------------------------|------------------------------------|-----------------------|
| DETACHED LISTS | MM (INCH) | DFTD Roy | DATE 11/20/2012 | | RoHS Compliant |
| | TOLERANCES EXCEPT AS NOTED | CHKD | DATE | | |
| | MM | APPVL | DATE | TITLE USB 3.0 MICRO BF SMD TYPE | |
| | .0 | MATERIAL : | | | |
| | .00 | ANGLES: X.*±1° X.X.*±0.5° | QTY : | DRAWING NO. E8110-030-01 | |
| .000 | | FINISH : | /PART NO. E8110-030-01 | | |
| | THIRD ANGLE PROJECTION | SCALE : 1:1 | DO NOT SCALE DRAWING | | SHEET 2 OF 2 |